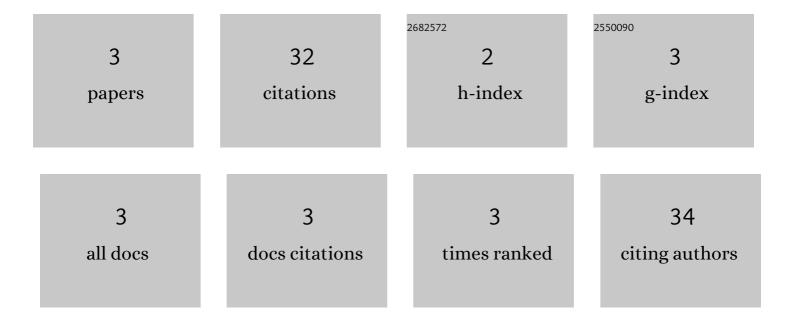


## List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/5996643/publications.pdf

Version: 2024-02-01



Li Du

#	Article	IF	CITATIONS
1	Analysis on annealing-induced stress of blind-via TSV using FEM. Frontiers of Mechanical Engineering, 2018, 13, 401-410.	4.3	3
2	Using RBF networks for detection and prediction of flip chip with missing bumps. Microelectronics Reliability, 2015, 55, 2817-2825.	1.7	9
3	Optimization of through silicon via for three-dimensional integration. Microelectronic Engineering, 2015, 139, 31-38.	2.4	20